## 54ACT16952, 74ACT16952 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCAS159C - JANUARY 1991 - REVISED APRIL 1996

- Members of the Texas Instruments Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- Noninverting Outputs
- Two 16-Bit, Back-to-Back Registers Store Data Flowing in Both Directions
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

### description

The 'ACT16952 are 16-bit registered transceivers that contain two sets of D-type flip-flops for temporary storage of data flowing in either direction. They can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is stored in registers on the low-to-high transition of the clock (CLKAB or CLKBA) input, provided that the clock-enable (CEAB or CEBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port. To avoid false clocking of the flip-flops, CEAB (or CEBA) should not be switched from low to high while CLKAB (or CLKBA) is low.

54ACT16952 . . . WD PACKAGE 74ACT16952 . . . DL PACKAGE (TOP VIEW)



The 74ACT16952 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16952 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16952 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.



# 54ACT16952, 74ACT16952 **16-BIT REGISTERED TRANSCEIVERS** WITH 3-STATE OUTPUTS SCAS159C – JANUARY 1991 – REVISED APRIL 1996

#### **FUNCTION TABLE**†

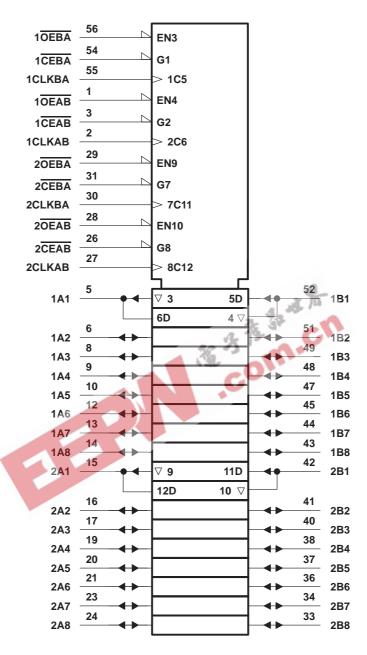
	INPU	TS		OUTPUT
CEAB	CLKAB	OEAB	Α	В
Н	Х	L	Х	В <sub>0</sub> ‡ В <sub>0</sub> ‡
Х	Н	L	Χ	в <sub>0</sub> ‡
L	$\uparrow$	L	L	L
L	$\uparrow$	L	Н	Н
Х	X	Н	Χ	Z

<sup>&</sup>lt;sup>†</sup> A-to-B data flow is shown; B-to-A data flow is similar but uses CEBA, CLKBA, and OEBA.

<sup>‡</sup>Level of B before the indicated steady-state input conditions were established



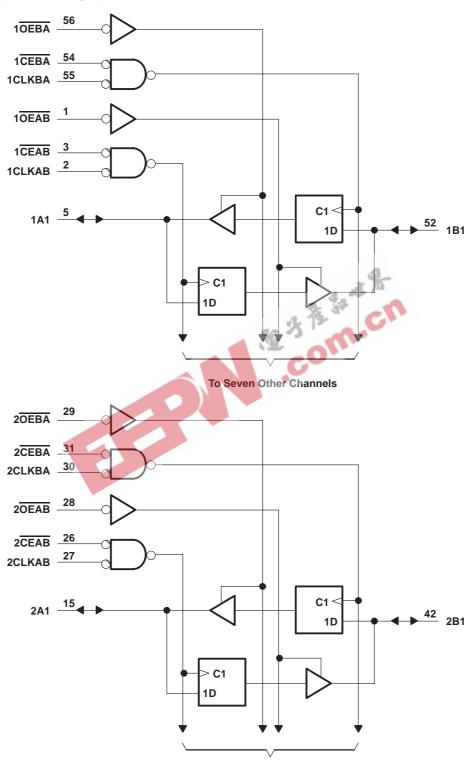
## logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# 54ACT16952, 74ACT16952 **16-BIT REGISTERED TRANSCEIVERS** WITH 3-STATE OUTPUTS SCAS159C – JANUARY 1991 – REVISED APRIL 1996

## logic diagram (positive logic)





To Seven Other Channels

## 54ACT16952, 74ACT16952 **16-BIT REGISTERED TRANSCEIVERS** WITH 3-STATE OUTPUTS SCAS159C – JANUARY 1991 – REVISED APRIL 1996

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V <sub>O</sub> (see Note 1)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{ K }$ ( $V_{ C }$ or $V_{ C }$ $V_{ C }$ )	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±400 mA
Maximum package power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.4 W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

		54ACT16952	74	74ACT16952	
		MIN NOM MAX	MIN	NOM MAX	UNIT
Vcc	Supply voltage	4.5 5 5.5	4.5	5 5.5	V
VIH	High-level input voltage	2	2		V
VIL	Low-level input voltage	3.0		0.8	V
VI	Input voltage	0 VCC	0	VCC	V
Vo	Output voltage	0 6 V <sub>CC</sub>	0	VCC	V
ІОН	High-level output current	-24		-24	mA
loL	Low-level output current	24		24	mA
Δt/Δν	Input transition rise or fall rate	0 10	0	10	ns/V
TA	Operating free-air temperature	<b>-</b> 55 125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150 °C and a board trace length of 750 mils.

## 54ACT16952, 74ACT16952 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCAS159C - JANUARY 1991 - REVISED APRIL 1996

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	RAMETER	TEST CONDITIONS	Vaa	T,	4 = 25°C	;	54ACT	16952	74ACT	UNIT	
FAI	KAWETEK	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		10.1 - 50.114	4.5 V	4.4			4.4		4.4		
		I <sub>OH</sub> = -50 μA	5.5 V	5.4			5.4		5.4		
\ \/ a		I <sub>OH</sub> = -24 mA	4.5 V	3.94			3.8		3.8		V
VOH		IOH = -24 IIIA	5.5 V	4.94			4.8		4.8		V
		I <sub>OH</sub> = -50 mA <sup>†</sup>	5.5 V								
		I <sub>OH</sub> = -75 mA <sup>†</sup>	5.5 V				3.85	3	3.85		
		10 50 uA	4.5 V			0.1		0.1		0.1	
		ΙΟL = 50 μΑ	5.5 V			0.1		0.1		0.1	٧
\ \/ ~ .		10. 24 mA	4.5 V			0.36		0.44		0.44	
VOL		I <sub>OL</sub> = 24 mA	5.5 V			0.36	2	0.44		0.44	
		I <sub>OL</sub> = 50 mA <sup>†</sup>	5.5 V				20				
		I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V				3	1.65		1.65	
II	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			±0.1		±1		±1	μΑ
loz <sup>‡</sup>	A or B ports	$V_O = V_{CC}$ or GND	5.5 V		26.	±0.5	-	±5		±5	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		2 13	8	$\Theta_{I}$	80		80	μΑ
ΔICC§		One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V	溢	20	0.9		1		1	mA
Ci	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		3						pF
C <sub>io</sub>	A or B ports	$V_O = V_{CC}$ or GND	5 V		12						pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted)

			T <sub>A</sub> = 2	25°C	54ACT	16952	74ACT	16952	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency		0	75	0	75	0	75	MHz	
t <sub>W</sub>	Pulse duration, CLK high or low		6.7		6.7	4	6.7		ns	
	Outer the hetera OLICA	Data	5		5	15.11	5		no	
t <sub>su</sub>	Setup time before CLK↑	CEAB or CEBA	6.5		6.5	71.	6.5		ns	
<b>.</b>	Hald Constitute OUK	Data	1		'81		1		ns	
th th	Hold time after CLK↑	CEAB or CEBA	0		0		0			

For I/O ports, the parameter IOZ includes the input leakage current.

<sup>§</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.

## 54ACT16952, 74ACT16952 **16-BIT REGISTERED TRANSCEIVERS** WITH 3-STATE OUTPUTS SCAS159C - JANUARY 1991 - REVISED APRIL 1996

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T <sub>A</sub> = 25°C			54ACT16952		74ACT16952		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
f <sub>max</sub>			75			75		75		MHz
<sup>t</sup> PLH	CLK	A or B	4.7	8.5	10.7	4.7	11.8	4.7	11.8	ns
<sup>t</sup> PHL	CLK	AOIB	4.9	8.7	10.5	4.9	11.7	4.9	11.7	115
<sup>t</sup> PLH	OFDA OFAB	A or B	4.7	8.5	10.7	4.7	11.8	4.7	11.8	ns
<sup>t</sup> PHL	CEBA or CEAB		4.9	8.7	10.5	4.9	11.7	4.9	11.7	
<sup>t</sup> PZH	OFPA - OFAB	A or P	3.4	8.1	10.2	3.4	11.2	3.4	11.2	no
<sup>t</sup> PZL	OEBA or OEAB	A or B	4.2	9.6	11.8	4.2	13	4.2	13	ns
<sup>t</sup> PHZ	OFDA OFAB	A or P	5.2	7.5	8.9	5.2	9.4	5.2	9.4	no
<sup>t</sup> PLZ	OEBA or OEAB	A or B	4.5	6.7	8.2	4.5	8.7	4.5	8.7	ns

## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

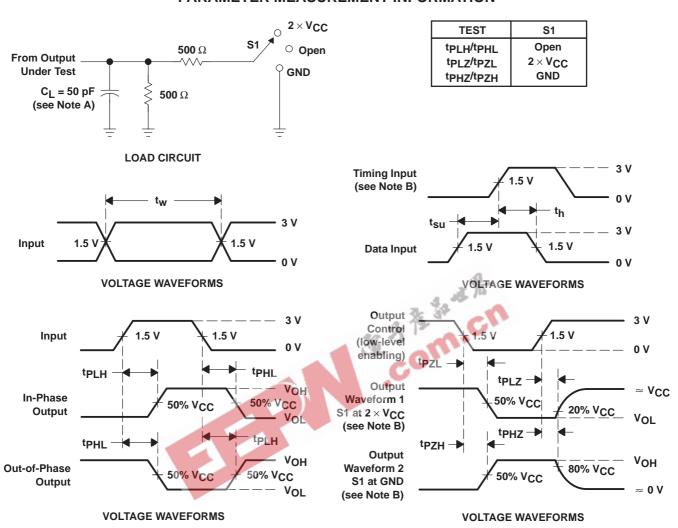
	PARAMETER		۵	TEST CON	NDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per transceiver	Outputs enabled	CL	= 50 pF,	f = 1 MHz	55	pF



## 54ACT16952, 74ACT16952 **16-BIT REGISTERED TRANSCEIVERS** WITH 3-STATE OUTPUTS

SCAS159C - JANUARY 1991 - REVISED APRIL 1996

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





### PACKAGE OPTION ADDENDUM

24-Feb-2006

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ACT16952DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16952DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16952DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16952DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): Ti's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

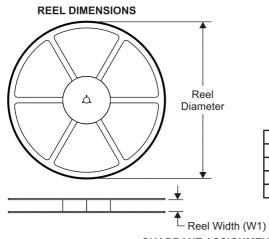
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

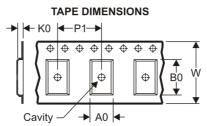


## **PACKAGE MATERIALS INFORMATION**

11-Mar-2008

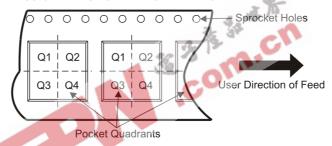
## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPES



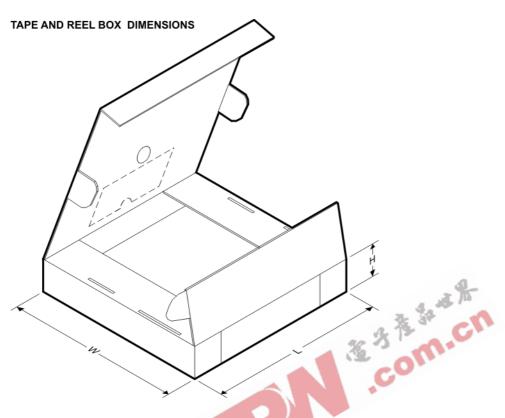
### \*All dimensions are nominal

Device		Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadra
74ACT16952DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





11-Mar-2008



## \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16952DLR	SSOP	DL	56	1000	346.0	346.0	49.0

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

**Products** Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

**Applications** Audio www.ti.com/audio Automotive www.ti.com/automotive Broadband www.ti.com/broadband Digital Control www.ti.com/digitalcontrol Medical www.ti.com/medical Military www.ti.com/military Optical Networking www.ti.com/opticalnetwork Security www.ti.com/security Telephony www.ti.com/telephony Video & Imaging www.ti.com/video Wireless www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated